

ABSTRACT

The present invention relates to a heat dissipation type semiconductor package with a heat-radiating canopy molded thereon and a method of fabricating the same.

5 According to the present invention, there is provided a heat dissipation type semiconductor package including a die paddle, a semiconductor chip mounted on the die paddle, and a lead frame. The heat dissipation type semiconductor package is characterized by comprising wires for electrically connecting bond pads formed on the semiconductor chip and inner leads in the lead frame; a heat-radiating canopy bonded on a top surface of the semiconductor chip; and a molding material for surrounding all of the die paddle, the semiconductor chip, the inner leads and a bottom surface of the heat-radiating canopy.

10 The top surface of the heat-radiating canopy is exposed to the exterior, and a portion of the surface of the heat-radiating canopy, which is in contact with the semiconductor chip, is recessed.